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FTDI Introduces Highly Sophisticated Single-Chip Solution for USB Full Speed Bridging

Easy to implement HID class IC features both USB-to-I²C & USB-to-UART functionality

23rd February 2016 - FTDI Chip continues to explore innovative new approaches for ensuring that USB technology is as straightforward to use as possible. The new FT260 is a human interface device (HID) class interface controller IC, which complements the company's expansive vendor class portfolio. It can provide USB 2.0 Full Speed (12Mbps) connectivity to a broad range of application scenarios **-** including connection of touchscreens, computer peripherals and IoT sensing apparatus, as well as USB interfacing of microcontroller or programmable logic centric system designs, plus industrial automation equipment and USB instrumentation. Supplied in compact 28-pin SSOP and 28-pin QFN package options, these USB bridge chips have dual HID interface support, with I²C and UART bus conversion capabilities.

As the entire USB protocol is handled on the chip, the FT260 offering presents engineers with a plug-and-play solution that is simple to incorporate into

contemporary embedded system designs. These ICs employ standard class drivers, which means it is not necessary to worry about installing complex vendor-specific drivers. Their flexible IOs mean they are compatible with 1.8V to 3.3V systems. During full operation only 24mA of current is drawn and this drops to just 385µA when in suspend mode.

The FT260 is the first device of its kind to be compliant with the HID-over-I^2C protocol, as specified by Microsoft with the release of Windows 8. A total of 4 different speed modes can be utilized while in I^2C bus - standard mode (SM), fast mode (FM), fast mode plus (FM+) and high speed (HS) with 7-bit addressing supported. The integrated memory resource enables storage of customized USB descriptors. The built-in oscillator PLL dispenses with the need for an external crystal - thereby saving space and lowering bill of materials costs. Furthermore, unlike competing ICs, the FT260 has USB battery charger detection mechanism included, so that more efficient charging may be benefitted from. To further assist engineers, this IC will be backed up by a series of board level products.

For more information on the FT260 visit: http://www.ftdichip.com/ft260/

About FTDI Chip

FTDI Chip develops innovative silicon solutions that enhance interaction with the latest in global technology. The major objective from the company is to 'bridge technologies' in order to support engineeers with highly sophisticated, feature-rich, robust and simple-to-use product platforms. These platforms enable creation of electronic designs with high performance, low peripheral component requirements, low power budgets and minimal board real estate.

FTDI Chip's long-established, continuously expanding Universal Serial Bus (USB) product line boasts such universally recognized product brands as the ubiquitous R-Chip, X-Chip, Hi-Speed and SuperSpeed USB 3.0 series. In addition to both host and bridge chips, it includes highly-integrated system solutions with built-in microcontroller functionality. The company's Embedded Video Engine (EVE) graphic controllers each pack display, audio and touch functionality onto a single chip. The unique, streamlined approach utilised by these ICs allow dramatic reductions in the development time and bill-of-materials costs involved in next generation Human Machine Interface (HMI)

implementation. FTDI Chip also provides families of highly-differentiated, speed-optimised microcontroller units (MCUs) with augmented connectivity features, specifically designed with compatibility to its USB and Display product lines in mind. These MCUs are targeted for key applications where they can add value with their superior processing performance and high levels of operational efficiency.

FTDI Chip is a fab-less semiconductor company, partnered with the world's leading foundries. The headquarter is located in Glasgow, UK and is supported with research and development facilities in Glasgow, Singapore and Taipei (Taiwan) plus regional sales and techical support sites in Glasgow, Taipei, Tigard (Oregon, USA) and Shanghai (China).

For more information go to http://www.ftdichip.com

For further information and reader enquiries:
Steven van der Wolf - FTDI Chip
Unit 1, 2 Seaward Place, Centurion Business Park, Glasgow, G41 1HH, UK
Tel: +44 (0) 141 429 2777 Fax: +44 (0) 141 429 2758
E-mail: marketing@ftdichip.com

Issued by:
Mike Green - Pinnacle Marketing Communications Ltd
Tel: +44 (0)20 84296543
E-mail: m.green@pinnaclemarcom.com
Web: www.pinnacle-marketing.com

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